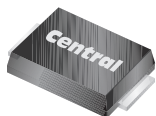


Material Composition Specification

SMBFL Case



Device average mass 50 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.54%	0.77	Si	7440-21-3	1.54%	0.77	15,400
leadframe	copper alloy	50.08%	25.038	Cu	7440-50-8	50%	25	500,000
				Fe	7439-89-6	0.08%	0.038	760
die attach	high temperature solder paste	4.95%	2.476	Pb	7439-92-1	4.58%	2.29	45,800
				Sn	7440-31-5	0.25%	0.124	2,480
				Ag	7440-22-4	0.12%	0.062	1,240
encapsulation*	EMC GREEN	42.23%	21.116	silica (fused)	60676-86-0	32.52%	16.26	325,200
				epoxy resin	29690-82-2	4.22%	2.11	42,200
				phenol resin	9003-35-4	4.1%	2.05	41,000
				carbon black	1333-86-4	0.13%	0.063	1,260
				metal hydroxide	1309-42-8	1.27%	0.633	12,660
plating	matte tin	1.2%	0.6	Sn	7440-31-5	1.2%	0.6	12,000

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (13-August 2012)